

BZX84WCx Zener Voltage Regulator Diode in SC-70

1 Features

- Total power dissipation: 360mW (max)
- Low I/O capacitance: 80pF (max)
- Low leakage current: 0.6µA (max)
- Tolerance: ±5%
- Temperature range: -55°C to +150°C
- Leaded package used for automatic optical inspection (AOI)

2 Applications

- Voltage regulation
- Over-voltage protection

3 Description

The BZX84WCx is a family of voltage regulating diodes in a SC-70 package. The diodes are available in Zener voltages ranging from 8.2V to 39V.

Package Information

PART NUMBER	PACKAGE ⁽¹⁾	PACKAGE SIZE ⁽²⁾
BZX84WCx	DCK (SC-70, 3)	2.00mm × 2.10mm

- (1) For more information, see [Section 9](#).
- (2) The package size (length × width) is a nominal value and includes pins, where applicable.

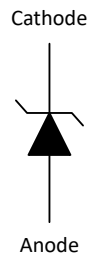


Figure 3-1. Functional Block Diagram



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4 Device Comparison Table

ZENER FAMILY	POWER DISSIPATION	PACKAGE
BZX84Cx / BZX84Cx-Q1	250mW	SOT-23
BZX84WCx / BZX84WCx-Q1	360mW	SC-70
SZMM3Zx ⁽¹⁾ / SZMM3Zx-Q1 ⁽¹⁾	300mW	SOD323
SZMM5Zx ⁽¹⁾ / SZMM5Zx-Q1 ⁽¹⁾	290mW	SOD523

(1) Preview Information (not Production Data)

5 Pin Configuration and Functions

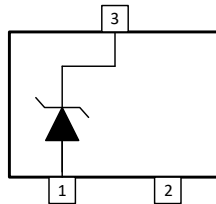


Figure 5-1. DCK Package, 3-Pin SC-70 (Top View)

Table 5-1. Pin Functions

PIN		DESCRIPTION
NO.	NAME	
1	A	Anode
2	NC	No Connect
3	K	Cathode

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
P_D ^{(2) (3)}	Total Power Dissipation		360	mW
I_F	Forward Current		200	mA
T_A	Ambient Operating Temperature	-55	150	°C
T_{stg}	Storage Temperature	-65	155	°C

(1) Operation outside the Absolute Maximum Ratings may cause permanent device damage. Absolute maximum ratings do not imply functional operation of the device at these or any other conditions beyond those listed under Recommended Operating Conditions. If briefly operating outside the Recommended Operating Conditions but within the Absolute Maximum Ratings, the device may not sustain damage, but it may not be fully functional. Operating the device in this manner may affect device reliability, functionality, performance, and shorten the device lifetime.

(2) FR-4 printed circuit board, single sided copper, standard footprint

(3) Measured at 25°C

6.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
V_F	Forward Voltage	$I_F = 10\text{mA}$		0.9	V
T_A	Operating free-air temperature	-55		150	°C

6.3 Thermal Information

THERMAL METRIC ⁽¹⁾		BZX84WCx	UNIT
		DCK (SC-70)	
		3 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	345.0	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	223.0	°C/W
R _{θJB}	Junction-to-board thermal resistance	159.0	°C/W
Ψ _{JT}	Junction-to-top characterization parameter	113.6	°C/W
Ψ _{JB}	Junction-to-board characterization parameter	157.9	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

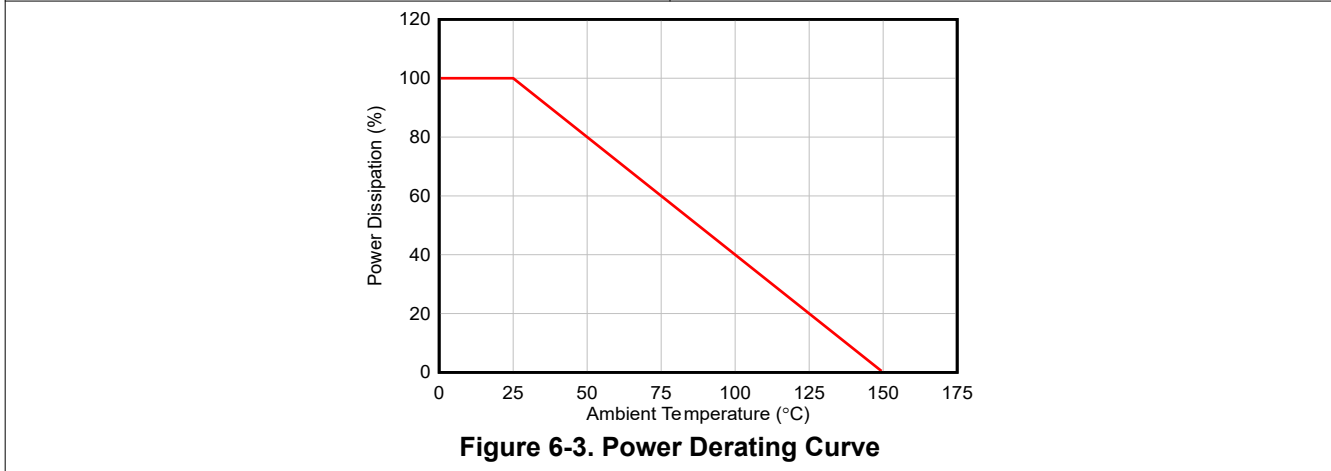
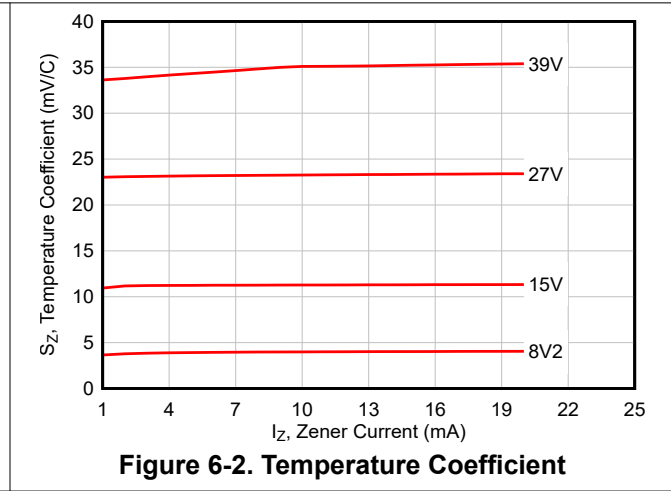
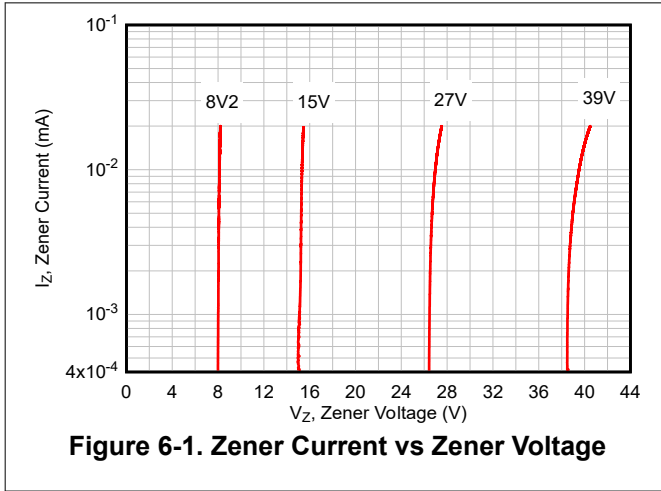
6.4 Electrical Characteristics

At T_A = 25°C (unless otherwise noted)

Part Number	Zener Voltage V _Z (V) at I _Z				Zener Impedance Z _{ZT} (Ω) at I _Z		Reverse Leakage Current I _R (μA)		Temperature Coefficient S _Z (mV/C) at I _Z		Capacitance C _D (pF) ⁽¹⁾
	MIN	TYP	MAX	I _Z (mA)	MAX	I _Z (mA)	MAX	V _R (V)	MAX	I _Z (mA)	MAX
BZX84WC8V2	7.79	8.2	8.61	5	15	5	0.6	5.75	6.2	5	80
BZX84WC15V	14.25	15	15.75	5	30	5	0.03	10.5	13	5	50
BZX84WC27V	25.65	27	28.35	2	80	2	0.03	18.9	25.3	2	35
BZX84WC39V	37.05	39	40.95	2	130	2	0.03	27.3	41.2	2	25

(1) f = 1MHz, V_R = 0

6.5 Typical Characteristics



7 Device and Documentation Support

7.1 Documentation Support

7.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, [Diodes Packaging and Layout Guide](#)
- Texas Instruments, [Diodes Layout Guide user's guide](#)
- Texas Instruments, [Generic Evaluation Module user's guide](#)

7.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

7.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

7.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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7.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

8 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision * (February 2025) to Revision A (April 2025)	Page
• Added BZX84WC39V device.....	1

DATE	REVISION	NOTES
February 2025	*	Initial Release

9 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BZX84WC27VDCKR	ACTIVE	SC70	DCK	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-55 to 150	1UN	Samples
BZX84WC8V2DCKR	ACTIVE	SC70	DCK	3	3000	RoHS & Green	SN	Level-1-260C-UNLIM	-55 to 150	1T1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF BZX84WC27V, BZX84WC8V2 :

- Automotive : [BZX84WC27V-Q1](#), [BZX84WC8V2-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

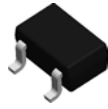
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BZX84WC27VDCKR	SC70	DCK	3	3000	180.0	8.4	2.3	2.75	1.2	4.0	8.0	Q3
BZX84WC8V2DCKR	SC70	DCK	3	3000	180.0	8.4	2.3	2.75	1.2	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BZX84WC27VDCKR	SC70	DCK	3	3000	210.0	185.0	35.0
BZX84WC8V2DCKR	SC70	DCK	3	3000	210.0	185.0	35.0

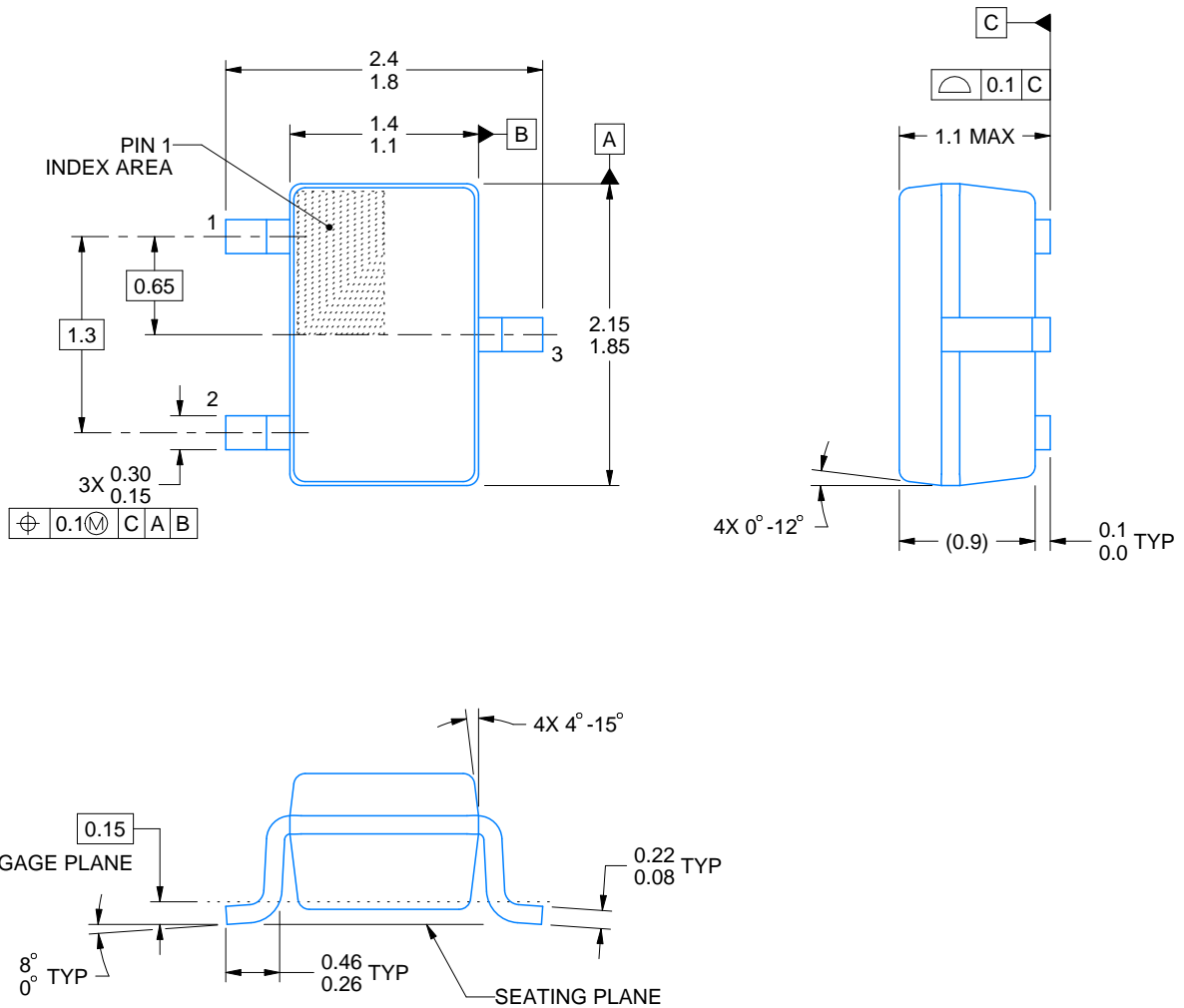
DCK0003A



PACKAGE OUTLINE

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



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NOTES:

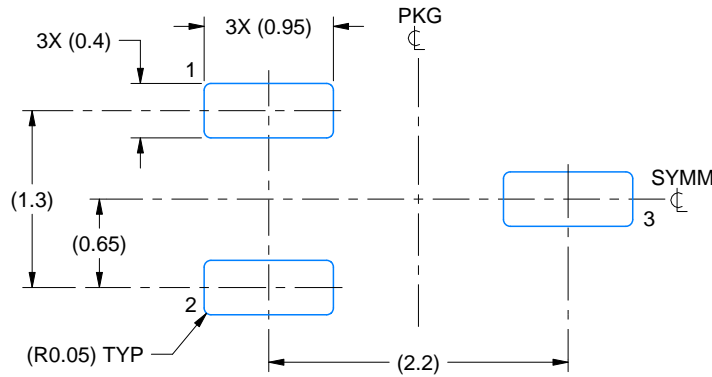
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

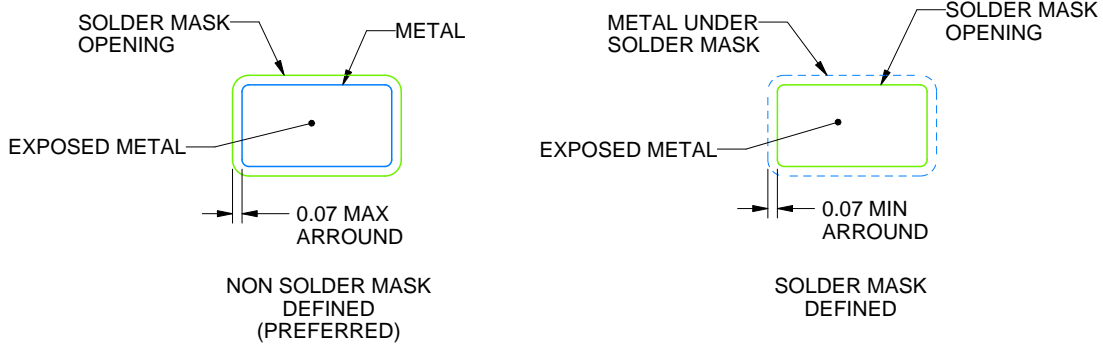
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SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X



SOLDER MASK DETAILS

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NOTES: (continued)

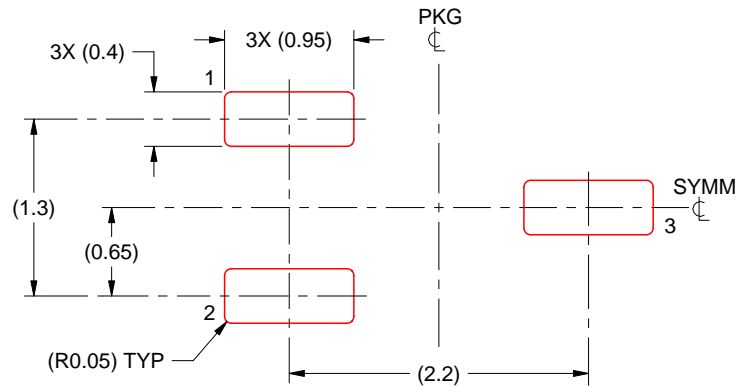
- 4. Publication IPC-7351 may have alternate designs.
- 5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DCK0003A

SOT-SC70 - 1.1 max height

SMALL OUTLINE TRANSISTOR SC70



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
7. Board assembly site may have different recommendations for stencil design.

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